TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

Notification# 20160411001
Datasheet for DDA0008J Package Drawing update
Information Only

Date: 4/11/2016
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20160411001
Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS5430DDA	null
TPS5430DDAR	null
TPS5431DDAR	null
TPS5431DDA	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20160411001	**PCN Date:**	04/11/2016
Title:	Datasheet for DDA0008J Package Drawing update		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Change Type:			

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being update to Update DDA0008J Package Drawing.

Devices Affected:

HPA00295DDAR, TPS5430DDA, TPS5430DDA-P, TPS5430DDAG4, TPS5430DDAR, TPS5430DDAR-P, TPS5430DDARG4, TPS5431DDA, TPS5431DDAG4, TPS5431DDAR, TPS5431DDARG4, TPS56527DDA, TPS56527DDAR.

Package Outline:

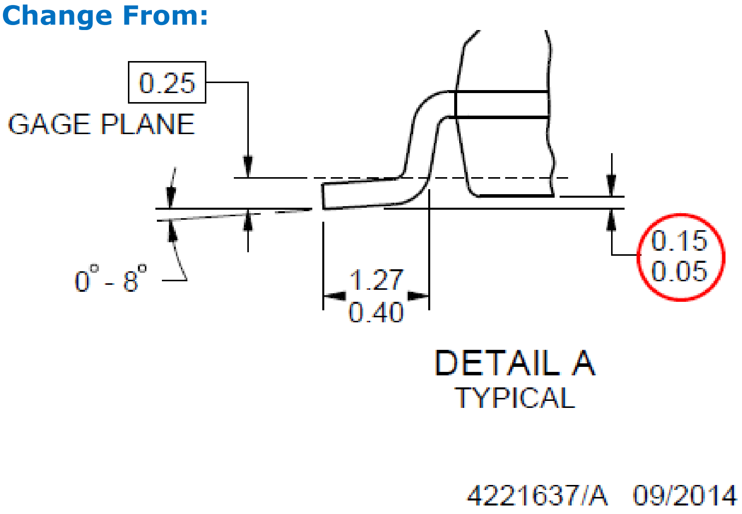
- DDA0008J 4221637 rev A to B

Drawing Changes:

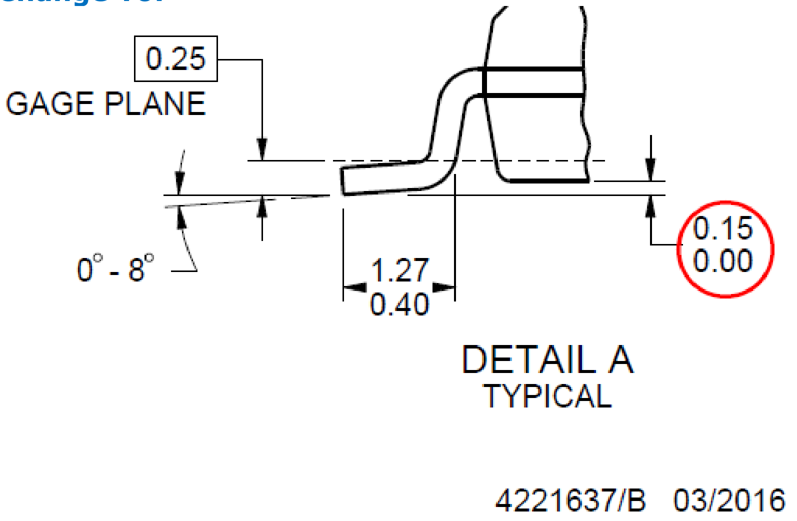
1. Minimum Standoff Height

   Drawing is being revised to correct a typo on the minimum value of the standoff which was inadvertently changed when the drawing was reformatted. It is now being reset to prior value which conforms to JEDEC Registration MS-012F

Change From:



Change To:



2. Minimum Dimensions Thermal Pad

   Thermal pad MIN dimensions are being modified to properly reflect the dimensions across our multiple manufacturing sources:

   Long side: From 2.9mm MIN to 2.5mm MIN
   Short side: From 2.4mm MIN to 2.0mm MIN

The updated datasheet(s) can be accessed at www.ti.com

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

There is no physical change to the packages; this is updating the documentation to match the parts. This change should have no effect on PCB designs as the land pattern should be designed to accommodate the MAX dimensions which have not changed. There are no changes to the board layout and stencil design examples.

Changes to product identification resulting from this PCN:

None.

Product Affected:

HPA00295DDAR	TPS5430DDAR	TPS5431DDA	TPS5431DDARG4
TPS5430DDA	TPS5430DDARG4	TPS5431DDAG4	TPS56527DDA
TPS5430DDAG4	TPS5430DDAR-P	TPS5431DDAR	TPS56527DDAR
TPS5430DDA-P			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com